

10/564220
IAP20 Reg'd PCT/PTO 11 JAN 2006

Attorney Docket No. 36856.1405

DESCRIPTION

PIEZOELECTRIC DEVICE

BACKGROUND OF THE INVENTION

1. Technical Field of the Invention

[0001] — The present invention relates to piezoelectric devices, and in particular relates to a piezoelectric device having piezoelectric elements using a piezoelectric substrate and a piezoelectric thin film, such as a resonator~~resonators~~ and a filter.

2. Description of the Related Background Art

[0002] — Recently, a chip-size package (CSP) has been developed in which that a piezoelectric device, such as a surface_acoustic_wave filter (SAW filter) including using a piezoelectric substrate and a bulk-acoustic-wave filter (BAW filter) including using a piezoelectric thin film, is miniaturized to until an element chip size.

— For example, a piezoelectric device 2 shown in Fig. 5 includes a piezoelectric substrate 3 having piezoelectric elements including IDTs (interdigital transducers, + interdigital electrodes) 4a and an electrically conductive pattern, such as pads 4b, provided formed on one principal surface 3a of the piezoelectric substrate 3, + a cover 6 covering the one principal surface 3a with a support layer 5 therebetween, + external electrodes 7, which are exposed

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International Application No.: PCT/JP2005/011169

U.S. Patent Application No.: Unknown

January 11, 2006

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AMENDMENTS TO THE SPECIFICATION:

A substitute specification and a marked-up copy of the English translation of the originally filed PCT application are attached hereto.

Please replace the Title of the Invention with the following new Title of the Invention:

PIEZOELECTRIC DEVICE

Please enter,
TMB 6-7-07

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